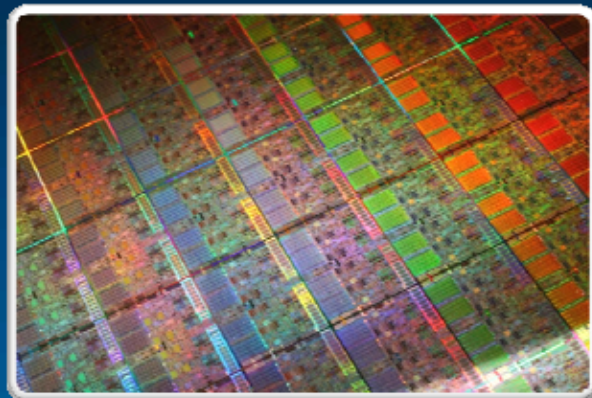


The background is a vibrant blue space filled with glowing, colorful circuit traces in shades of green, yellow, and purple. A bright cyan light source on the left creates a lens flare effect. In the lower-left foreground, two large, square silicon wafers are shown, their surfaces covered in intricate patterns of gold, blue, and red. The floor is a light blue grid that recedes into the distance. The overall aesthetic is futuristic and high-tech.

Invent the new reality.

Intel Developer  
**FORUM**

# Intel Architecture =



**Embedded**

**+**

**Dynamic**

**+**

**Visual**

**Pat Gelsinger**

Senior Vice President and Co-General Manager  
Digital Enterprise Group

# In Retrospect

*"We are heading toward a world of a billion – a billion connected computers."*



**Andrew S. Grove**  
Chairman & CEO, Intel Corporation  
IDF, February 17, 1998

*"Our vision is for a billion interconnected computers attached to the Internet. The mobile or wireless vision is a billion subscribers who can talk to each other and also have Internet access."*



**Craig Barrett**  
CEO, Intel Corporation  
IDF August 22, 2000

*"The vision of a billion connected phones and a billion connected handsets is happening. By 2010, those same trends will give us a 1.5B connected PCs, except this time, it's broadband. Those same trends will give us 2.5B connected handsets."*

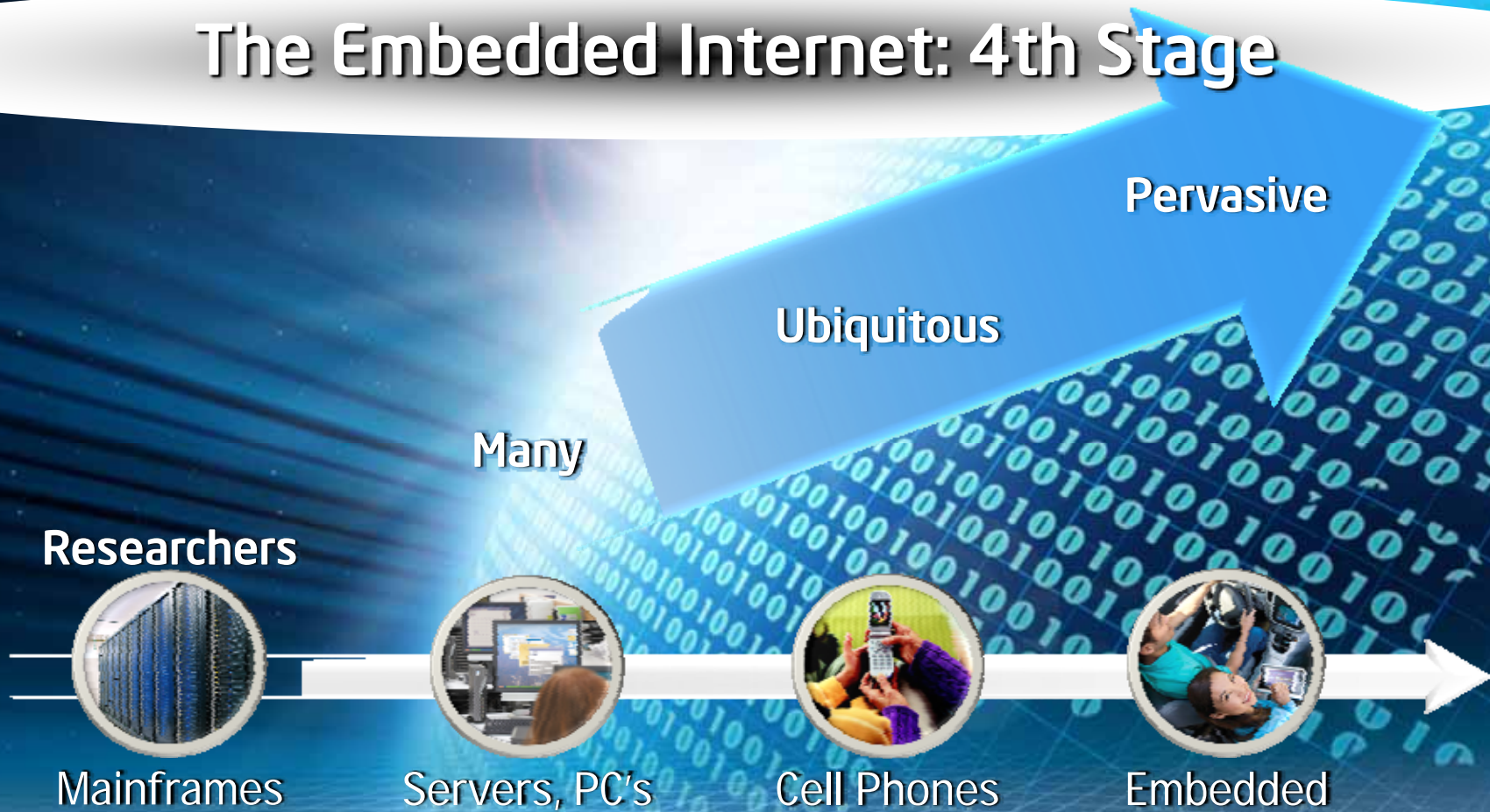


**Paul Otellini**  
President & COO, Intel Corporation  
IDF, Sept 23, 2003

# The Internet Today: 3rd Generation



# The Embedded Internet: 4th Stage



*Internet - 7x24, Every Modality of Life*

# The Embedded Internet by 2015

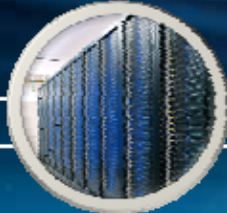
15B  
Devices

Pervasive

Ubiquitous

Many

Researchers



Mainframes



Servers, PC's



Cell Phones



Embedded

*Internet - 7x24, Every Modality of Life*

# The Next Wave of Devices



“Personal”



“Public”

# Towards 15B Devices by 2015

## Top Barriers

Reliability and Long Life

Software Scalability

Low Power and Low Cost

Privacy and Data Security

IPv4 Addressing

Open Standards



# Towards 15B Devices by 2015

## Top Barriers

Reliability and Long Life

Software Scalability

Low Power and Low Cost

Privacy and Data Security

IPv4 Addressing

Open Standards

## Solutions

Intel® Products

Intel Architecture

Intel® Atom™ Processor and SoCs

Encryption, Standards, Policy

Drive Towards IPv6 by 2012

Wifi, WiMAX, RFID, Bluetooth  
ZigBee, Z-Wave, LTE, P2P SIP, Open IPTV

# Serving the Embedded Segment Since 1976

1970's

1980's

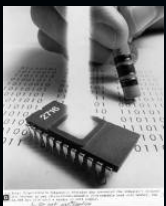
1990's

2000

2005



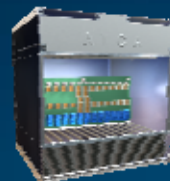
## Silicon



1<sup>st</sup>  
Integrated  
Chipset For  
Embedded

## Ecosystem

Intel Creates  
1<sup>st</sup> Embedded  
Ecosystem  
Program



## Market

Intel Enters  
Embedded  
Market  
Segment



Keynote at  
1<sup>st</sup> Embedded  
Systems  
Conference

Intel  
Revenue  
\$500M+ In  
Embedded

Intel  
Revenue  
\$1B+ In  
Embedded

*Embedded Market Segment Is Growing*

# Celebrating 30+ Years in Embedded



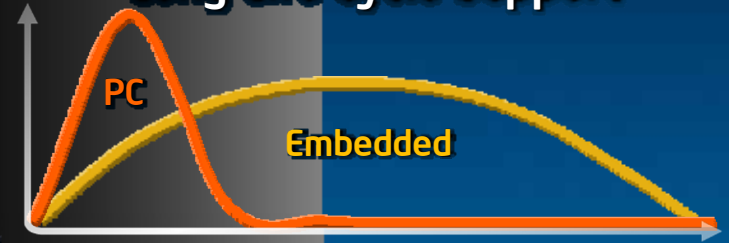
# The Preferred Architecture for Embedded Internet

## Scalable Architecture



Solutions from <1W-130W

## Long Life Cycle Support



Intel  
Architecture

## Purpose Built Solutions



## World's Best Ecosystem and Tools



# Embedded Products Today and Future

## Traditional Embedded IA



Desktop

Mobile

# Embedded Products Today and Future

## Traditional Embedded IA



Desktop



Mobile

## New Low Power IA



Introduced: April 2008

Fan-less

<5W Platform

Small Footprint

*~ 700 Embedded Customer Design Engagements  
Accelerating Conversion From Other Architectures*

# Embedded Products Today and Future

## Traditional Embedded IA



Desktop

Mobile

## New Low Power IA and SoCs for Embedded



Announced July 2008

First IA SOC since 80386EX in 1994

- Intel® QuickAssist Technology
- Communications I/O

Industrial temperature offering

45% area savings\*, 30% power savings\*

Q3'08 production



# Embedded Products Today and Future

## Traditional Embedded IA



Desktop

Mobile

## New Low Power IA and SoCs for Embedded



Q1'09



2H'09



# Home Automation

Open Architecture

Low-power

Small Form Factor



# IP Media Phones: *Resetting Expectations For The Home Phone*



# In-Vehicle Infotainment: *Bringing IT to the Car*



# Emerging Open Infotainment Platform

Design Services



Middleware and Applications



Board Vendors/ODMs



Operating Systems



Complimentary Auto Silicon



TV: Terrestrial/Satellite

Rich 3D GPS

Social Networking

Online Gaming

Video On Demand

Office Synch

NG Remote Diagnostics

*Supported by Broad Eco-System*

# Industry Momentum

*"BMW Group welcomes Intel's commitment to the automotive infotainment space, enabling us to **bridge the gap between current automotive implementations and the consumer sector.**"*

**Christoph Grote**

Senior Vice President Information &  
Communication Systems  
BMW Group



*"A more **open and standard approach to infotainment** product development will enable the automotive industry to more quickly **meet the consumer demands for Multimedia and Internet access.**"*

**Tsuguo NOBE**

General Manager  
NISSAN MOTOR CO., LTD.



*"With open infotainment platforms, our traditional tier 1 **suppliers could concentrate on using their engineering power to create new innovations** for us. I also expect quality improvements since multiple suppliers will be able to use and test the **same software.**"*

**Mr Häussermann**

VP Infotainment Development  
Daimler - Mercedes Benz

**DAIMLER**

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# In-Vehicle Infotainment

**Alex Busch**

Information and Communication Systems  
BMW Group

*"... the solution for the future could be to add vehicle-specific components and requirements to existing IT technology and make it suitable for use in cars."*



# The Embedded Internet by 2015

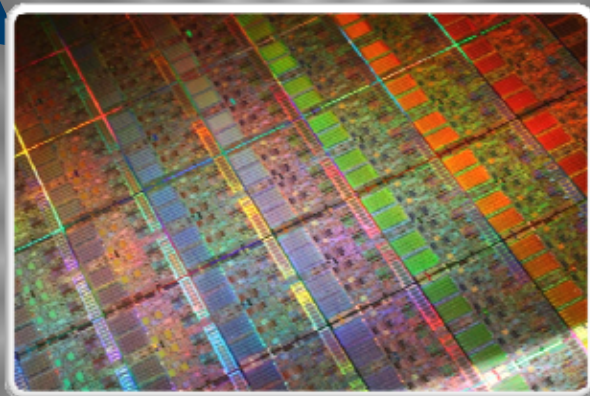


# Intel Architecture



**Embedded**

+



**Dynamic**

+

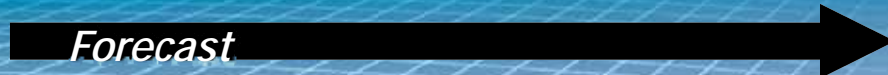


**Visual**



# Tick-Tock Development Model: *Predictable, Sustained Microprocessor Leadership*

| Intel® Core™  |   | Nehalem microarchitecture                              |   | Future uArch  |
|---|---|--|---|---|
| <b>Merom</b><br><br>NEW<br>Microarchitecture<br>65nm                    | <b>Penryn</b><br><br>NEW<br>Process<br>45nm | <b>Nehalem</b><br><br>NEW<br>Microarchitecture<br>45nm | <b>Westmere</b><br><br>NEW<br>Process<br>32nm | <b>Sandy Bridge</b><br><br>NEW<br>Microarchitecture<br>32nm |
| <i><b>TOCK</b></i>  | <i><b>TICK</b></i>                          | <i><b>TOCK</b></i>                                     | <i><b>TICK</b></i>                            | <i><b>TOCK</b></i>  |
| <b>Montecito /<br/>Montvale</b><br><br>NEW<br>Microarchitecture<br>90nm |   | <b>Tukwila</b><br><br>NEW<br>Microarchitecture<br>65nm |   | <b>Poulson</b><br><br>NEW<br>Microarchitecture<br>32nm      |



All dates, product descriptions, availability and plans are forecasts and subject to change without notice.

# Next Generation Intel® Itanium® (Tukwila)

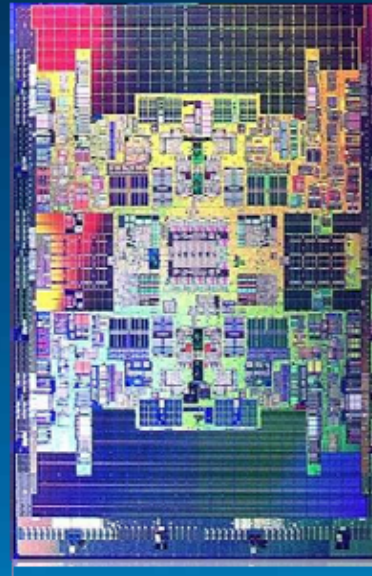
1<sup>st</sup> 2B transistor chip

Built for mission critical enterprise

- On-die error protection
- RAS
- Advanced power and thermal management

2<sup>nd</sup> generation Virtualization Technology

Strong roadmap with Poulson and Kittson



*"With Intel's upcoming quad-core Tukwila processor, Windows Server solutions running on Itanium-based systems will provide an even more scalable and reliable datacenter foundation for our customers."*

**Bill Laing**

Corporate Vice President  
Windows Server Division,  
Microsoft

***Business Critical Capabilities for Most Demanding Systems***

# Intel® Xeon® 7400 Series (Dunnington)

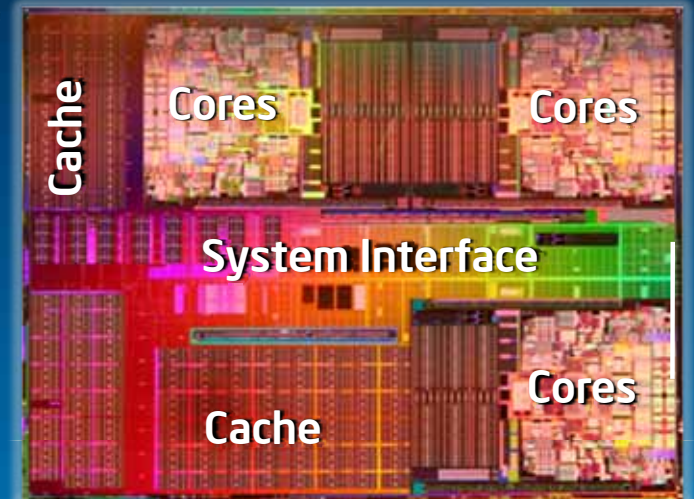
Virtualization platform of choice – just got better

Investment Protection

- Intel VT FlexMigration
- Socket compatible with Xeon™ 7300

45 nm high-k

- 6 cores
- 16MB shared L3 cache



*Extending MP Leadership in September 2008*

# Intel® Xeon® Processor 7400 Series: Setting New Enterprise Performance Records



TPC Benchmark\* C - DB2  
1,200,632 tpmC

**First 8S 1 M+ TPC-C database result for Xeon!**



TPC Benchmark\* C - SQL Server  
634,825 tpmC



SPECjbb\*2005 - - Java HotSpot  
JVM  
531,669 bops



TPC Benchmark\* C  
671.4 tpmC



vConsolidate -  
VMware\* ESX 39% better\*\*



SPECint\*\_rate2000  
277 peak score

*Unquestioned Expandable Server Leadership*

\*\*Intel Xeon X7460 (16M cache, 2.66GHz, 1066FSB) 6-Core compared to Intel Xeon X7350 (4M cache, 2.93GHz, 1066FSB) Quad-Core

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# Nehalem Family

Server and  
Workstation

Efficient  
Performance (2S)



Expandable (4S+)



Business and  
Consumer  
Clients

High End  
Desktop



Mainstream  
Client



Thin and Light  
Notebook



# Nehalem: Innovative New Architecture

2, 4 or 8 Cores

Integrated Memory Controller

QuickPath Interconnect

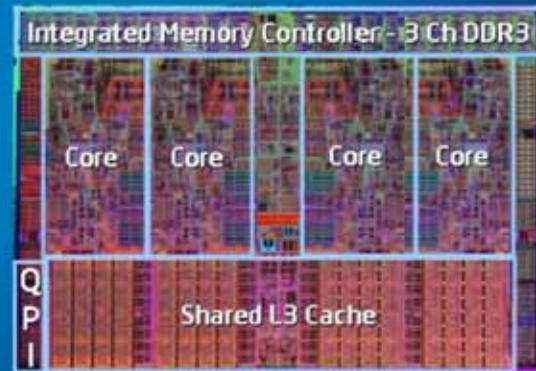
2-way Simultaneous Multi-threading

Microarchitecture Enhancements

Dynamic Power Management

SSE 4.2

Q4'08 Production



Fall 2007 IDF

Intel Developer  
FORUM  
Invent the new reality.



Invent the new reality.

Intel Developer  
FORUM

# Nehalem: Next Generation Micro-architecture

Energy Efficient Performance

Intel Hyper-Threading  
Technology

Turbo Mode

Dynamic Power Management



Nehalem

Intel's 2<sup>nd</sup> Generation  
Virtualization

3x Memory Bandwidth

Best in Class Bandwidth with QPI

*Industry's First Dynamically Scalable Architecture*



# Rajesh Kumar

Intel Fellow  
Director, Circuit & Low Power Technologies  
Intel Corporation



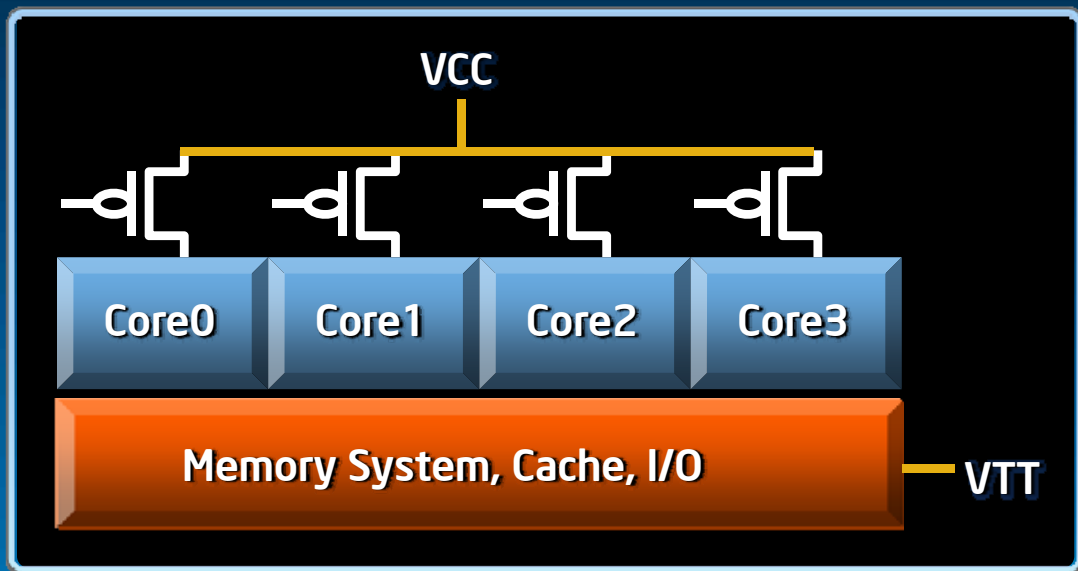
# Integrated Power Gate

## Clock Gate

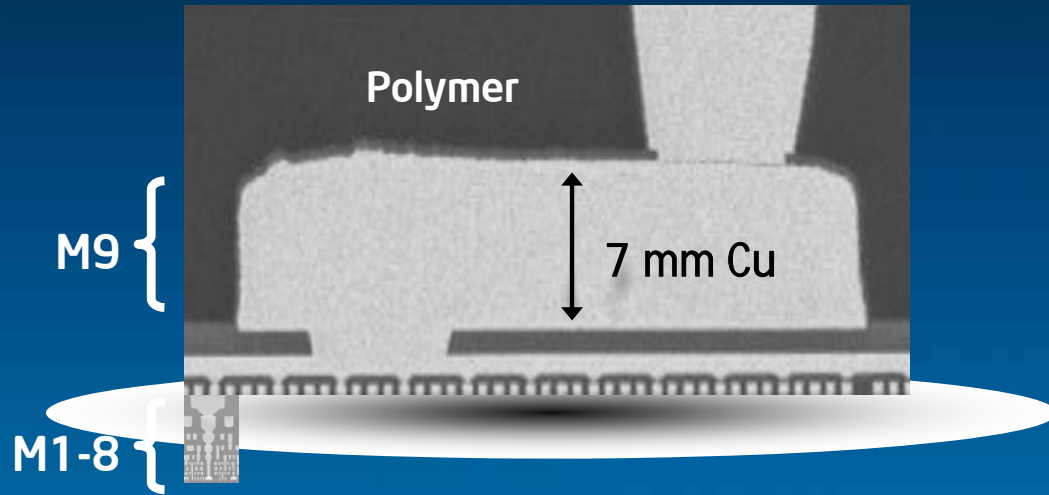
- Standard in all Intel CPUs
- Eliminates switching power
- Leakage power remains

## Power Gate: New

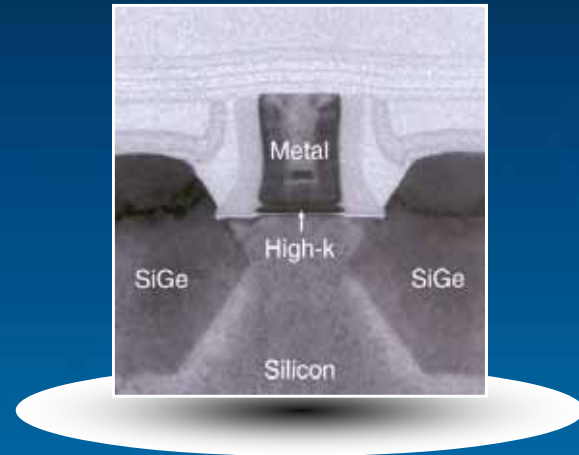
- Eliminates switching and leakage power
- Enables idle cores to go to near zero power (C6) independently
- Transparent to platform and software
- No incremental platform cost



# Power Gates Silicon Technology



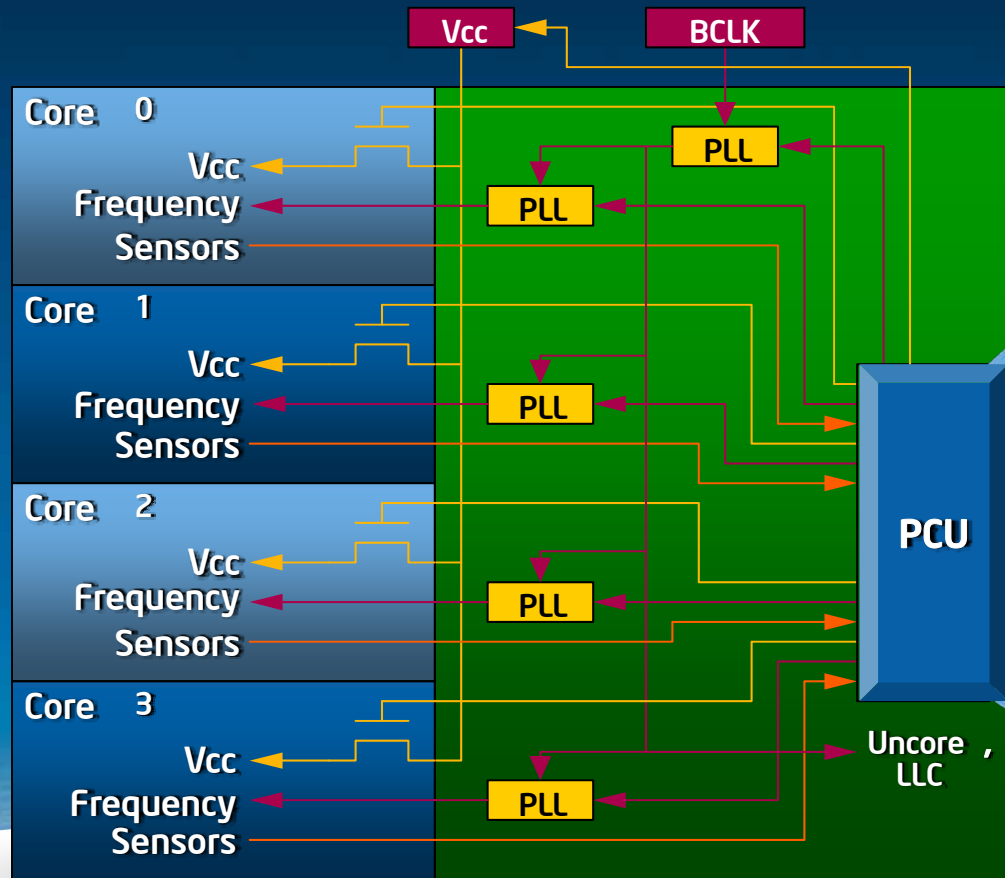
Package Like Metal (M9) Deposited On Silicon to Create Low On-resistance



Specialized, Ultra-low Leakage Transistor Developed for High Off-resistance

*Intel Design and Process Technology Co-development*

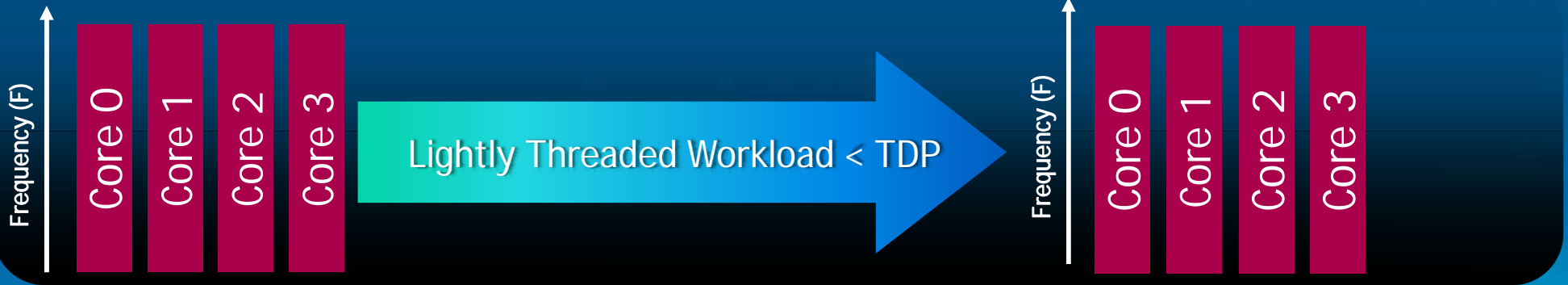
# Power Management: Power Control Unit



- Integrated microcontroller
- Controlled by firmware
- Real time sensors for current/ power, voltage, temperature
- Enables sophisticated algorithms for current operating conditions

# Nehalem Turbo Mode

No Turbo



# Nehalem Turbo Mode

Power Gates

Near Zero Power For Inactive Cores

No Turbo



# Nehalem Turbo Mode

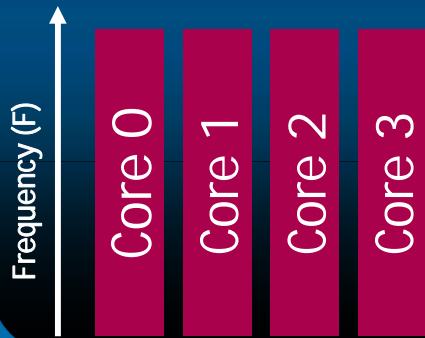
Power Gates

Near Zero Power For Inactive Cores

Turbo Mode

Adds Additional Performance Bins\*  
In Response To Workload

No Turbo



\*within power and thermal constraints

# Nehalem Turbo Mode

Power Gates

Near Zero Power For Inactive Cores

Turbo Mode

Adds Additional Performance Bins\*  
In Response To Workload

No Turbo



*Dynamically Delivering Optimal Performance and Energy Efficiency*

\*within power and thermal constraints

# Nehalem Innovations: Dynamic Power Management

Power Gates

Idle Cores Use Near Zero Power

Short Entry/Exit Latencies For C States

Available In All Segments

Broader Operating Voltage Range

Improves Scalability

Dynamic Only Load Line

Provides Lower Power at Same Performance



# Nehalem Family

Server and  
Workstation

Efficient  
Performance (2S)



Business and  
Consumer  
Clients

High End  
Desktop



*World's Most Adaptable Server Platform*

**Today's Focus:**

**HPC**

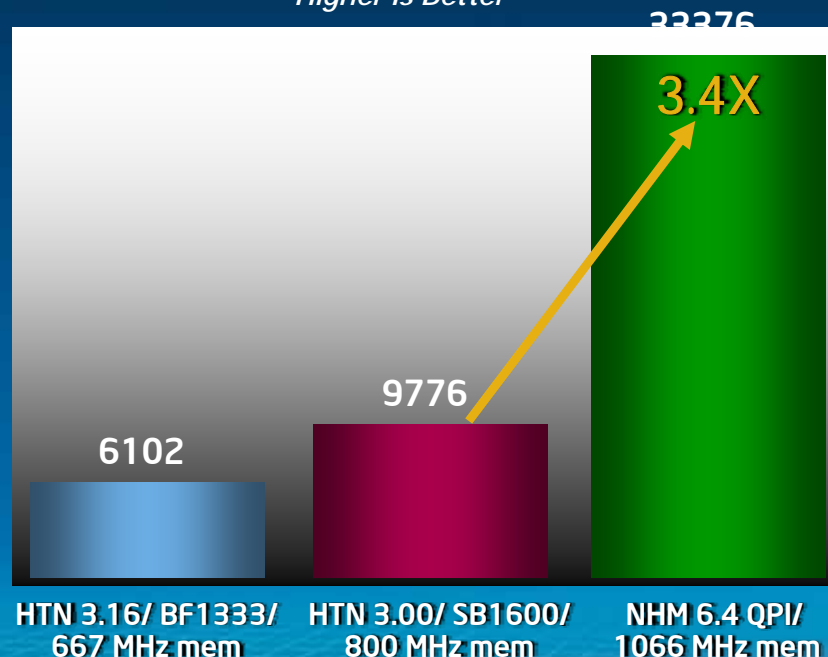
**Content Creation**

**Virtualization**

# Nehalem – EP

## Stream Bandwidth – Mbytes/Sec (Triad)

*Higher Is Better*



## Energy Efficient

- Performance on demand with Turbo mode
- Dynamic power management

## Outstanding Performance

- Best in class bandwidth with QPI up to 25.6 GB/s
- DDR3 and supports 18 DIMM up to 288 GB

## Designed for Virtualization

- Investment protection with FlexMigration
- Rapid VM migration with I/O optimizations

***World's Most Adaptable Server Platform***

Source: Intel Internal measurements – August 2008

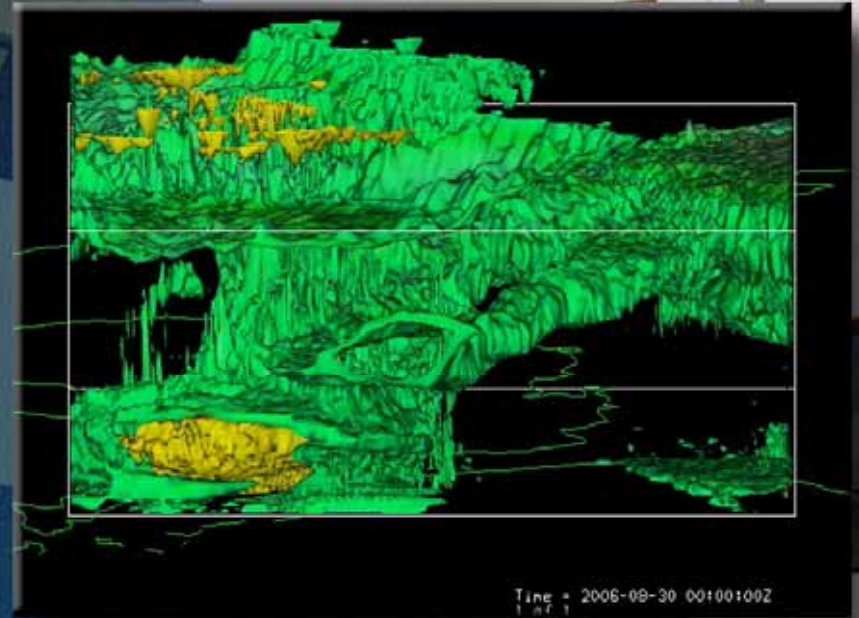
\* With 16 GB DIMMs

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# Nehalem – EP: HPC and Visual Problem Solving

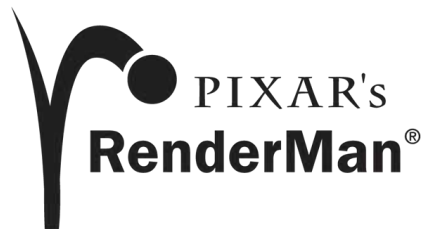
*“The next-generation processor (**Nehalem**) and system technology **will deliver a monumental increase in computing power**, enabling further advances in scientific discoveries and engineering achievements in support of future NASA missions.”*

**Rupak Biswas,**  
Director, NAS Division NASA



NASA Advanced Supercomputing Facility  
N-258

# The Content Industry Embraces IA



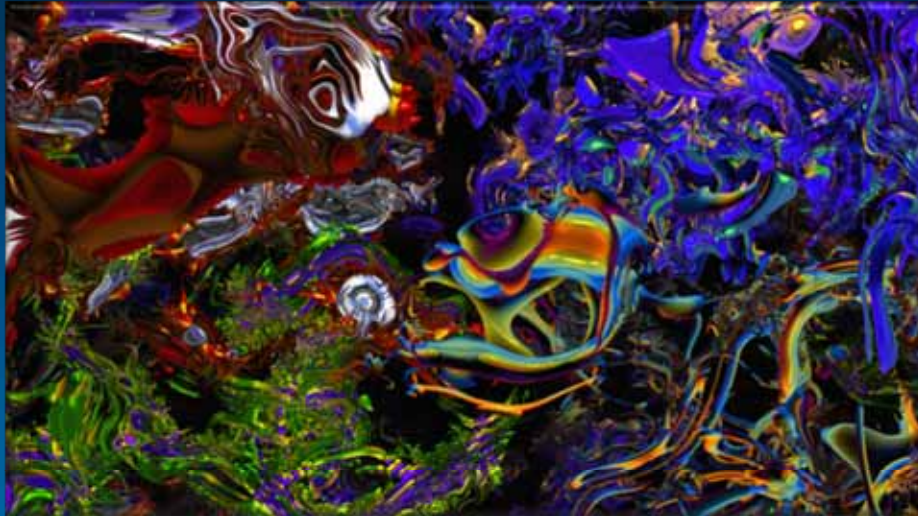
# Nehalem - EP: Advances in Content Creation

*"Nehalem enables the creation of vast new worlds of complexity that were inconceivable before. I'm reeling from an exploding universe of inspiring possibilities. The dream of creating extended high resolution animations of the elaborate visions in my mind's eye is finally becoming a reality."*

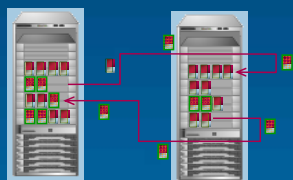
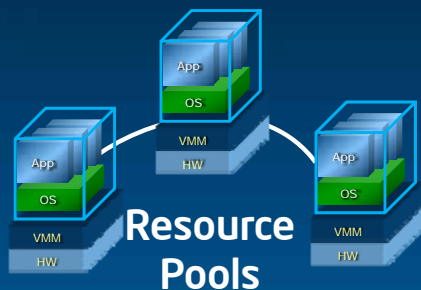
**Kevin Mack**

Oscar award-winning Digital Artist at Sony

# Nehalem - EP: Advances in Content Creation



# Nehalem Platform: Designed for Virtualization 2.0



VM Migrating  
over the network



**Flexible Workload Management**  
Intel VT FlexMigration

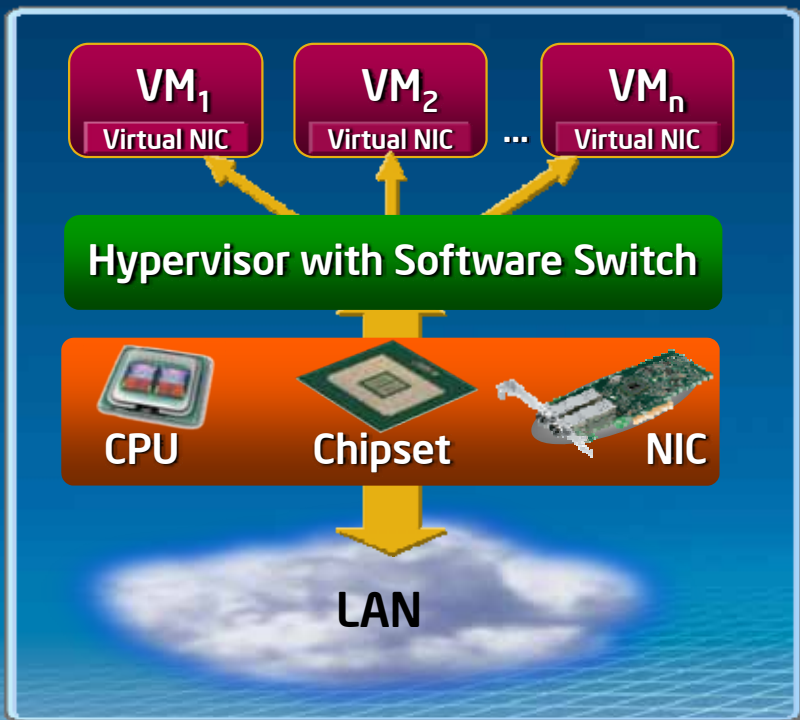
**Hardware and Software Evolution**  
New Capabilities: VT-x2, Intel Dynamic Power Manager  
Enabling Ecosystem Support

**I/O Designed for Virtualization**

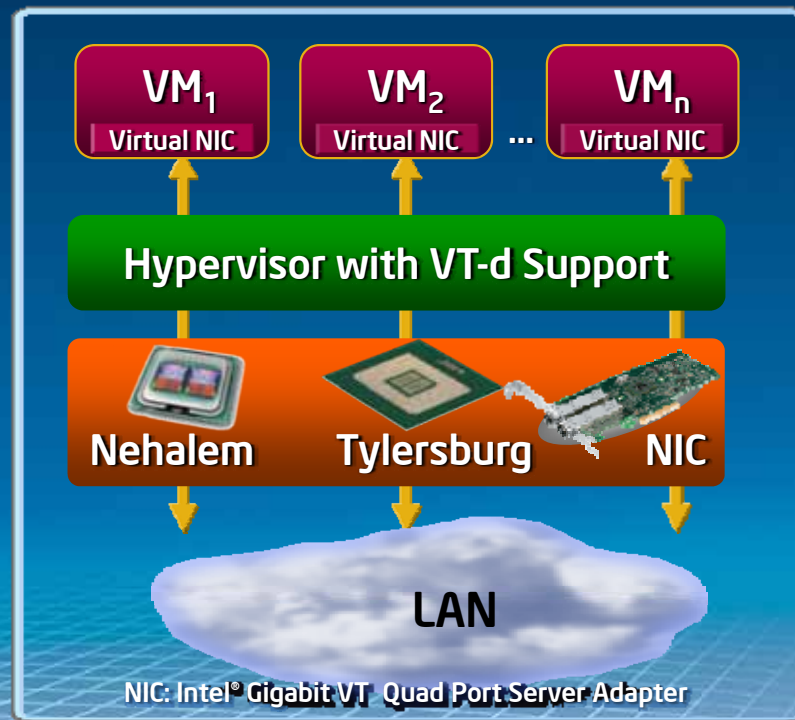
Intel VT for Connectivity  
Intel VT for Directed I/O: VT-d2  
Fiber Channel Over Ethernet

# Nehalem/Tylersburg VT-d Demo

No Intel VT-d:  
Software Switch Directs the Traffic



With Intel VT-d  
Direct Assignment to Guest VM



NIC: Intel® Gigabit VT Quad Port Server Adapter



# Intel and Microsoft: Virtualization Collaboration



Server Consolidation



Dev/Test



Business Continuity



Accelerated Provisioning



Dynamic Datacenter

## Intel® Dynamic Power Node Manager

- New dynamic approach to power budgeting for virtualized environment

Vary P-states and T-states for optimal performance/power ratios

*"Microsoft and Intel have worked together to optimize Hyper-V for Intel Virtualization Technology and support the upcoming Dunnington processor. We're already seeing outstanding performance from our complementary software and hardware, which together provide our customers with amazing capabilities."*

## Bob Muglia

Senior Vice President  
Microsoft Server & Tools Business



# Nehalem Family

Server and  
Workstation

Efficient  
Performance (2S)



Expandable (4S+)



Business and  
Consumer  
Clients

High End  
Desktop



Mainstream  
Client



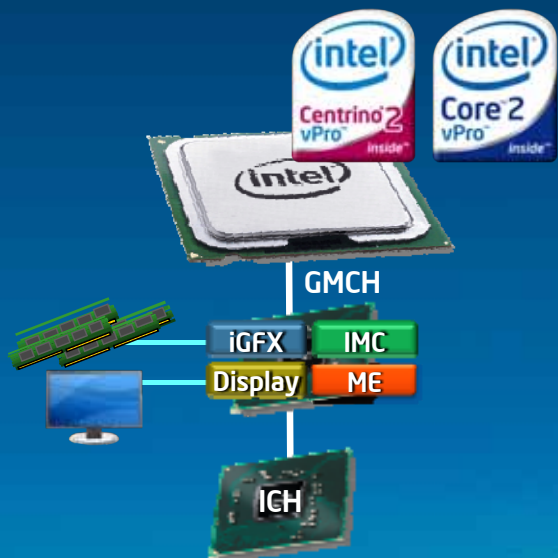
Thin and Light  
Notebook



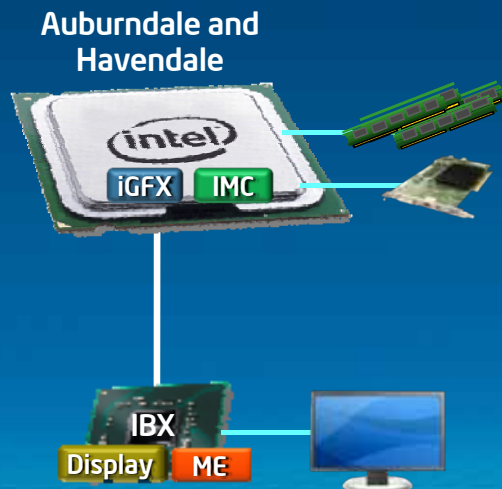
# Nehalem: Repartitioning the Client Platform

2008

Montevina and McCreary Platforms  
3 Chip Solution



Calpella and Piketon Platforms  
2 Chip Solution



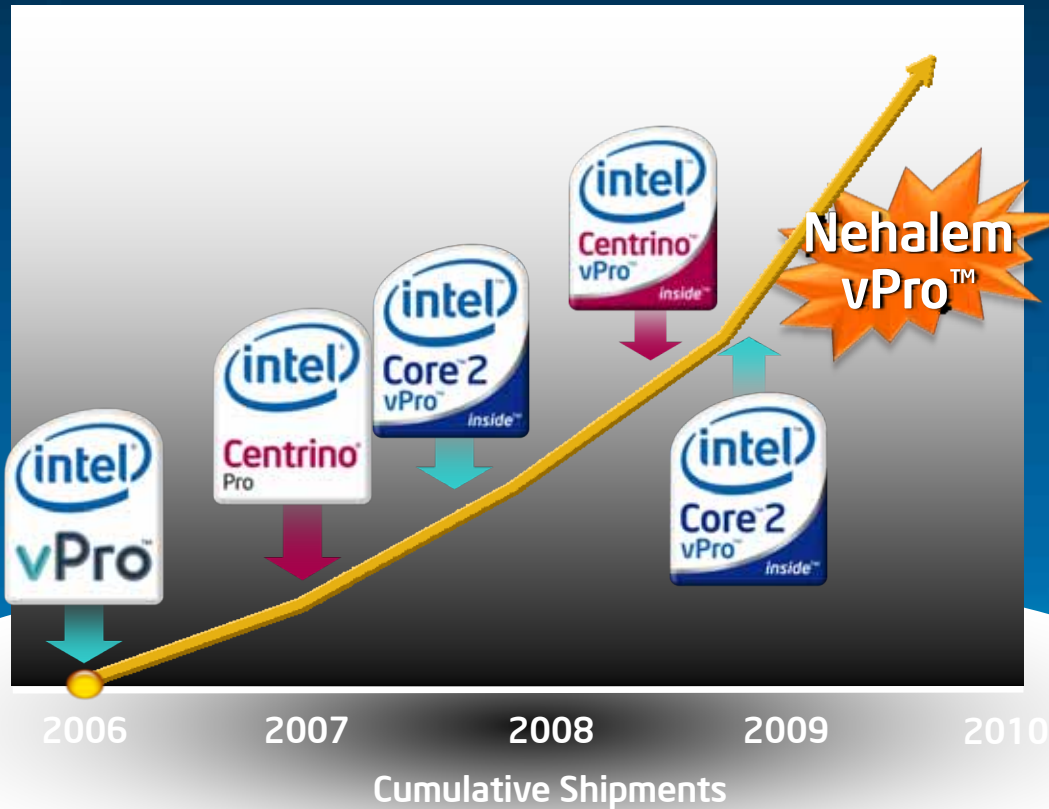
- Scalable : 2 to 4 Cores
- Integrated memory controller
- Intel® Hyper-Threading and Turbo mode

Introducing Ixex Peak:

- New product category
- Core platform capabilities

*Higher Integration, Leading Performance with Lower Power*

# Intel® vPro™: Critical Mass



60% of Fortune 100 Companies

All Leading OEMs

5000 Active Channel Partners

80+ ISV Partners

All Major Verticals

Worldwide

# Intel® vPro™: Customers Activating in Volume



25,000 Clients



80% Desk-side Visits



45% Power Expense



850,000 lbs CO<sub>2</sub> Emissions

472% 4-year ROI

# Unquestioned Leadership: Intel Core i7 Processor and X58 Chipset



4 cores - 8 threads

Intel® Hyper-Threading technology

Turbo mode

8 MB of Intel® Smart cache

Intel® QuickPath interconnect

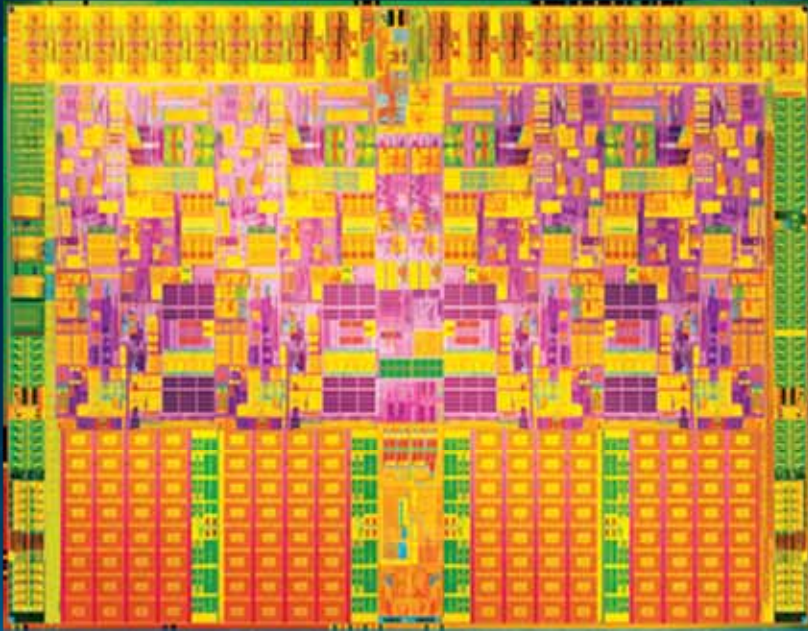
Integrated 3-ch DDR3 memory controller

PCI Express\* 2.0 for discrete graphics



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# IA is "Dynamic"



Nehalem is the First Dynamically Scalable  
Microarchitecture

World's Most Adaptable Server Platform

Extending Unquestioned Leadership

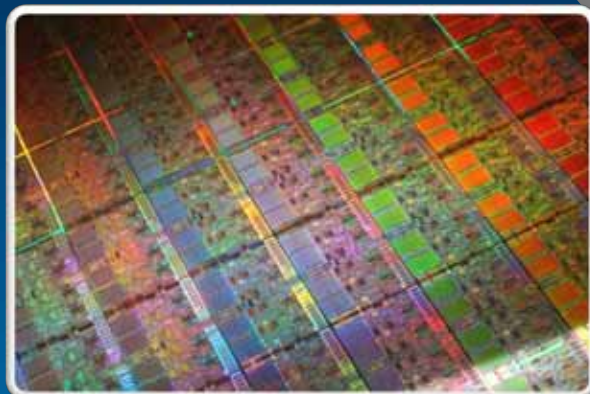


# Intel Architecture



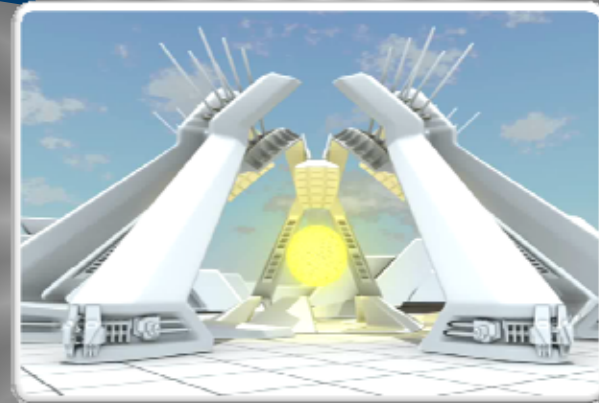
**Embedded**

+



**Dynamic**

+



**Visual**

# Visual Computing: Spring'08 IDF

## Visual Computing : What Does it Take?



Multi-threaded High-performance **CPU**



High Performance **Memory** and **I/O**



IA Programming, Software **Tools**, and **Support**



Integrated or Discrete **Graphics**  
**Larrabee**: Scalable Many-core IA Architecture



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**FORUM**  
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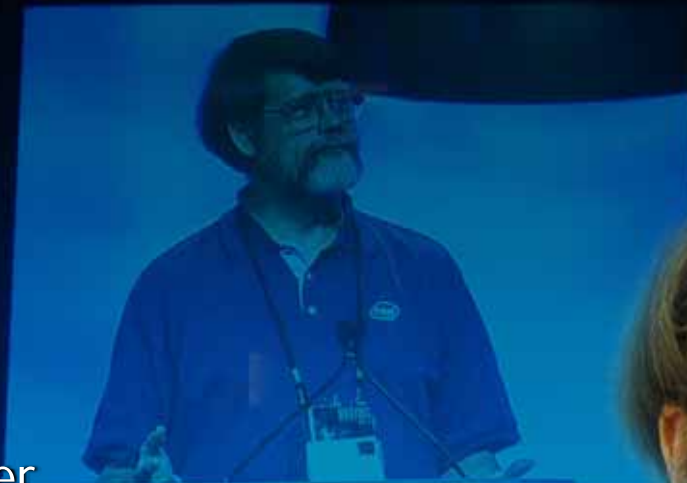


Intel Developer  
**FORUM**  
Invent the new reality.

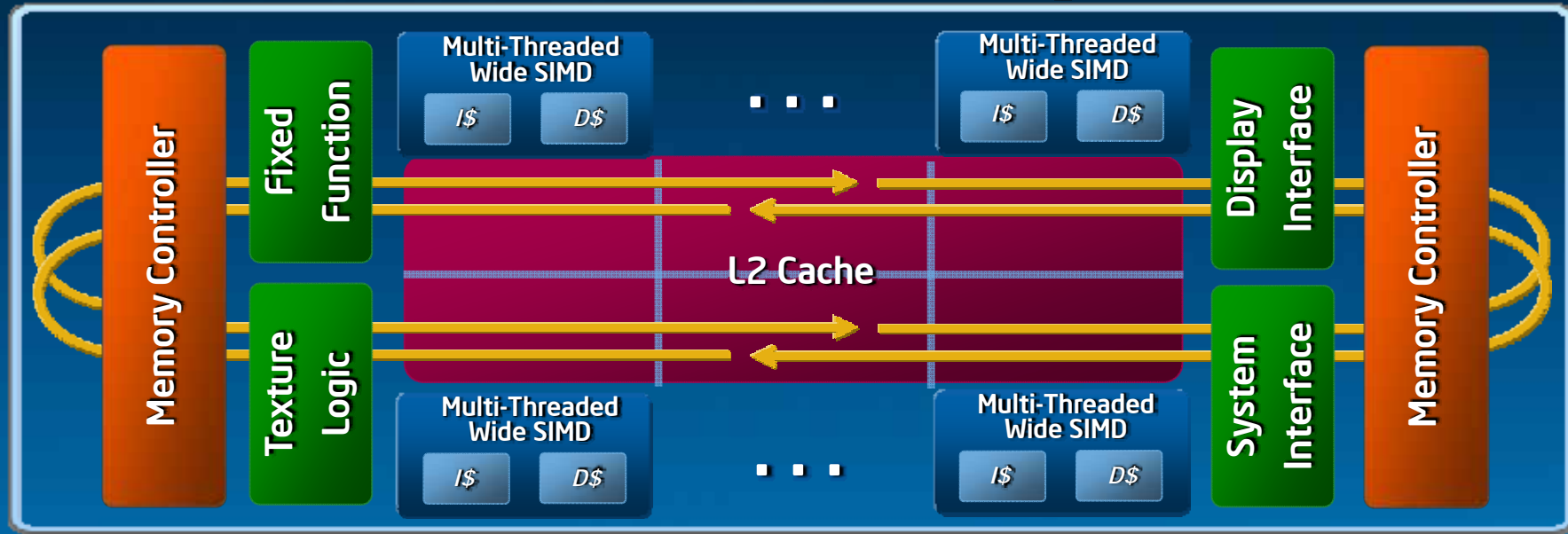
Invent the new reality. **Intel Developer FORUM**

# Larry Seiler

Sr. Principal Engineer,  
Visual Computing Group  
Intel Corporation



# Larrabee: Block Diagram



- **Multiple IA cores**

- In-order, short pipeline
- Multi-thread support

- **16-wide vector units**

- Extended instruction set

- **Fully coherent caches**

- **1024-bit ring bus**

- **Dedicated texture logic**

- Supports virtual memory

# Transparency Example without Sorting



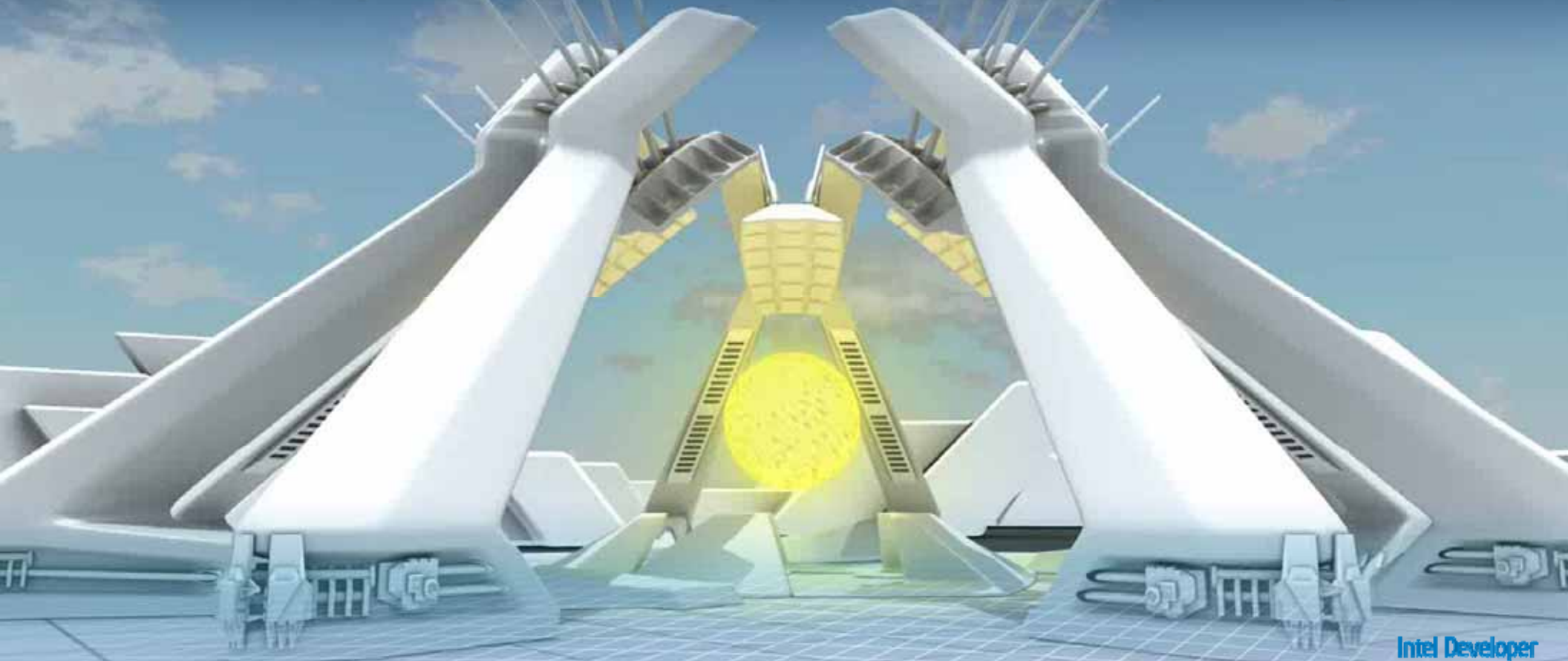
*The small dragon was drawn first, so its translucent wing pops through the wing of the large dragon.*

# Transparency Example with Sorting



*The translucent pixels are sorted so that the small dragon's wing is drawn behind the large dragon.*

# Example: Object Independent Transparency



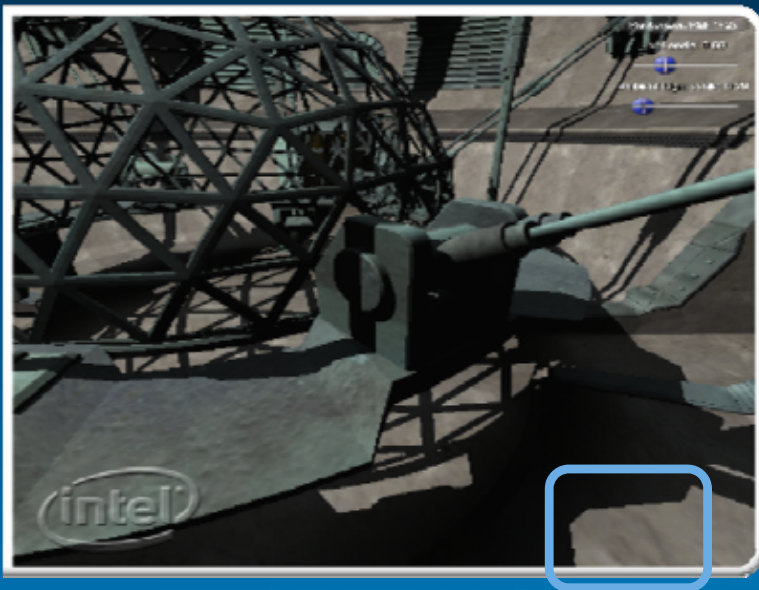
# Standard Shadow Map Algorithm



*Jagged Edge Artifacts Are Evident With Shadow Maps*

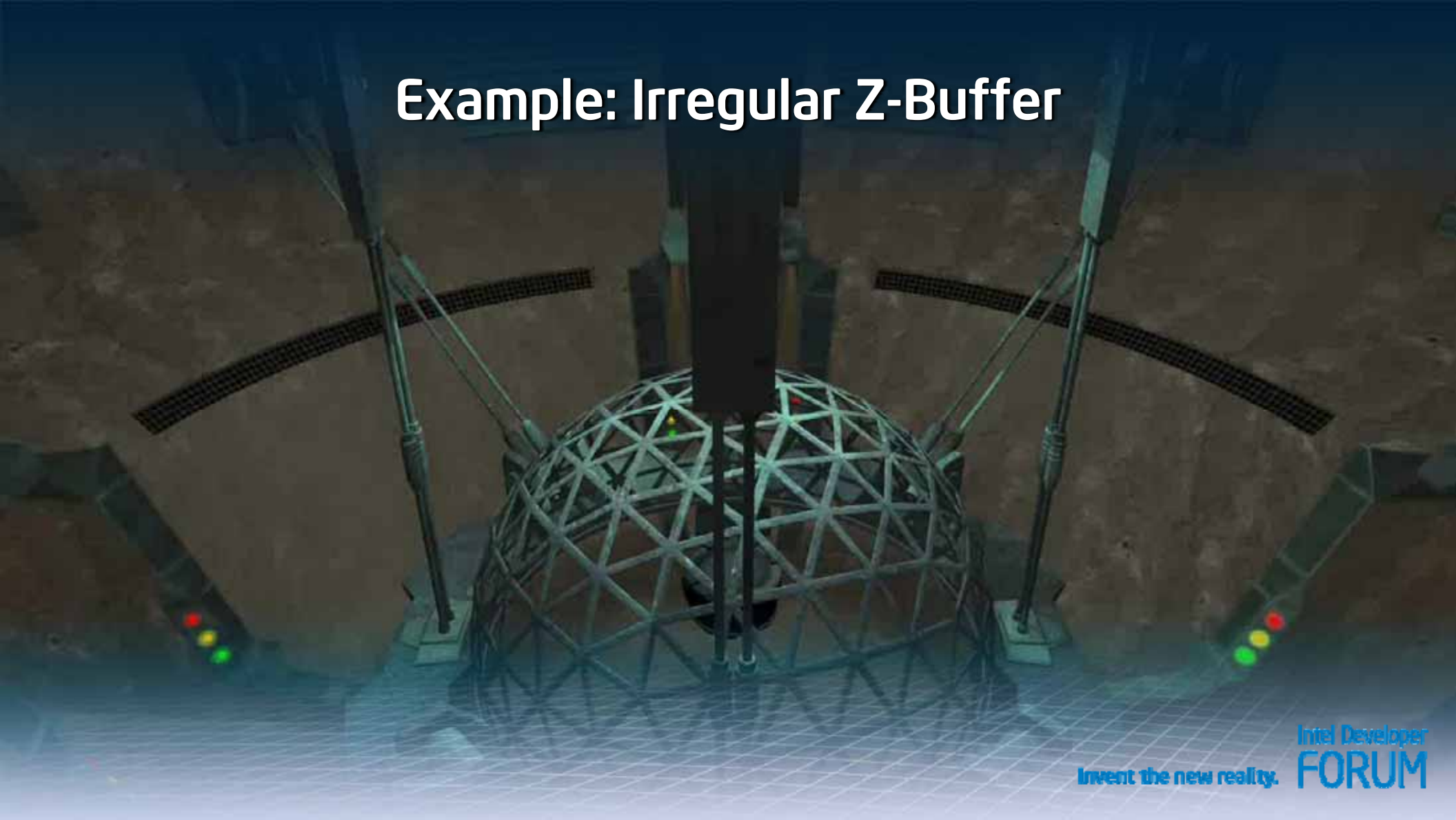


# Shadows with Irregular Z-Buffer

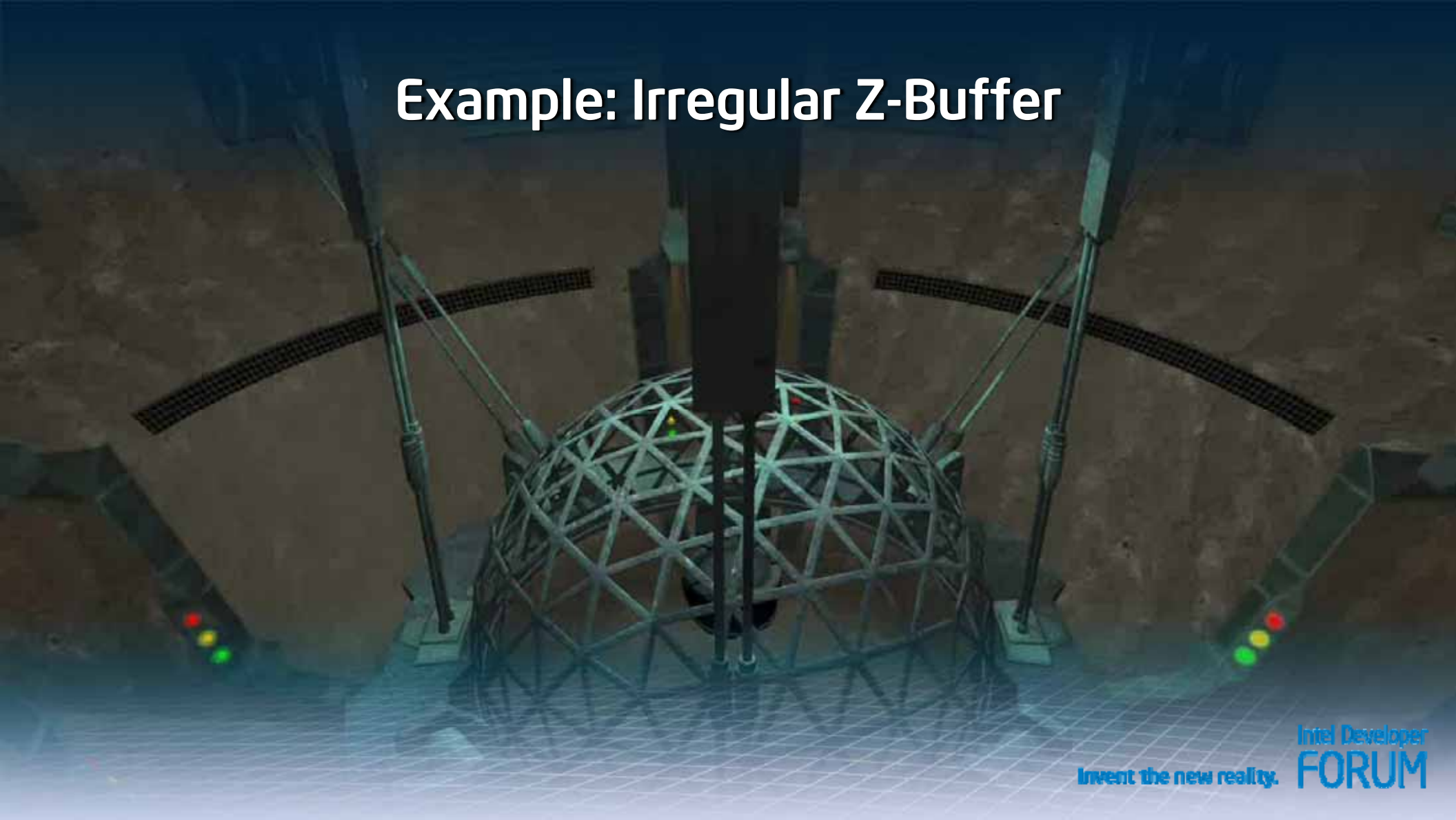


*With Irregular Z-buffer, Clean Edge Details Are Always Rendered*

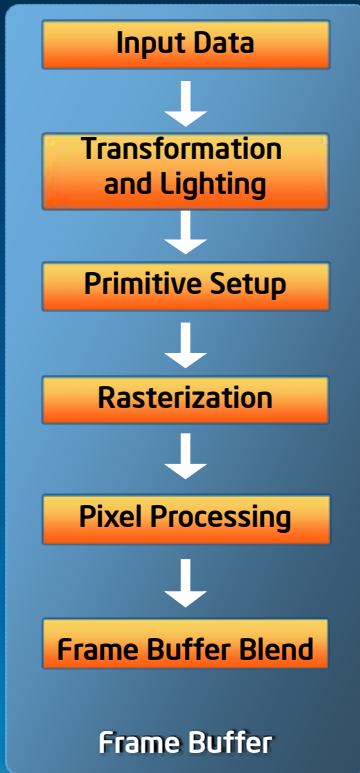
# Example: Irregular Z-Buffer



# Example: Irregular Z-Buffer



# GPUs Are More Computationally Efficient?



**Pre 2001:  
Fixed Function**

Early graphics processors

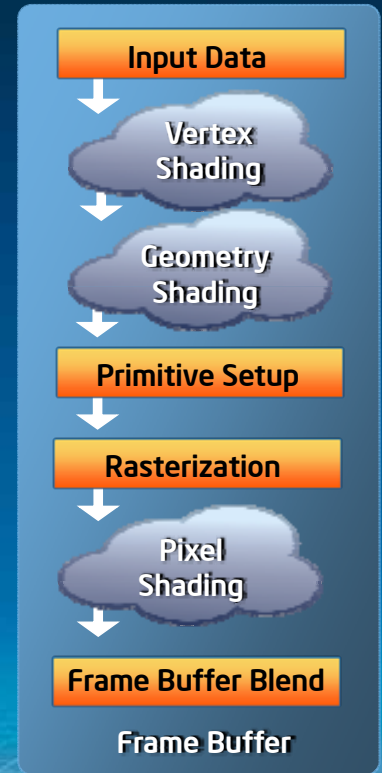
- Offloaded graphics from the CPU
- Simple, fixed function pipeline
- Many companies made products

GPU performance ramp

- 1.7x FLOPS increase per year \*
- High computational density gained by increased parallelism
- Also by larger die & more power

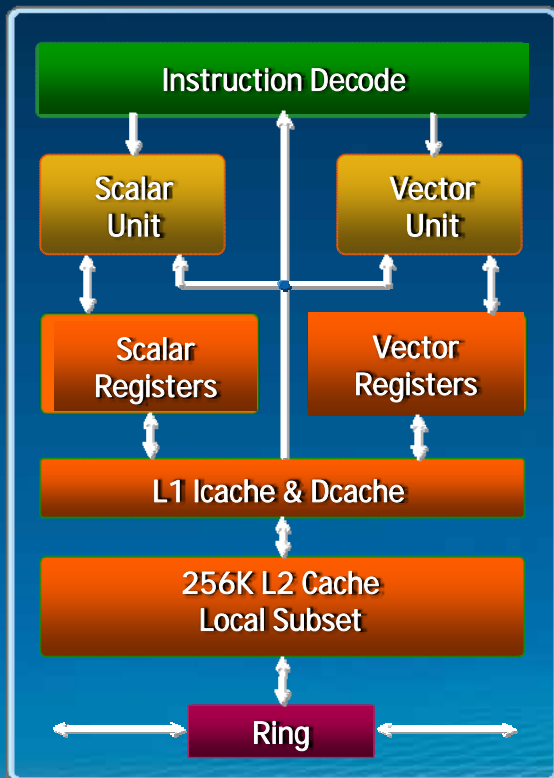
Changing graphics pipeline

- Programmable stages added
- Increasing design complexity
- Fewer companies involved

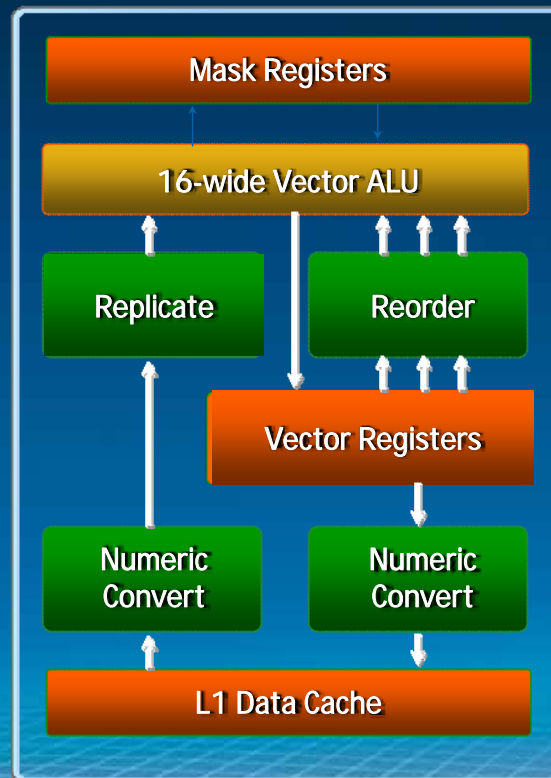


**Post 2006:  
Programmable**

# Larrabee: High Computational Density

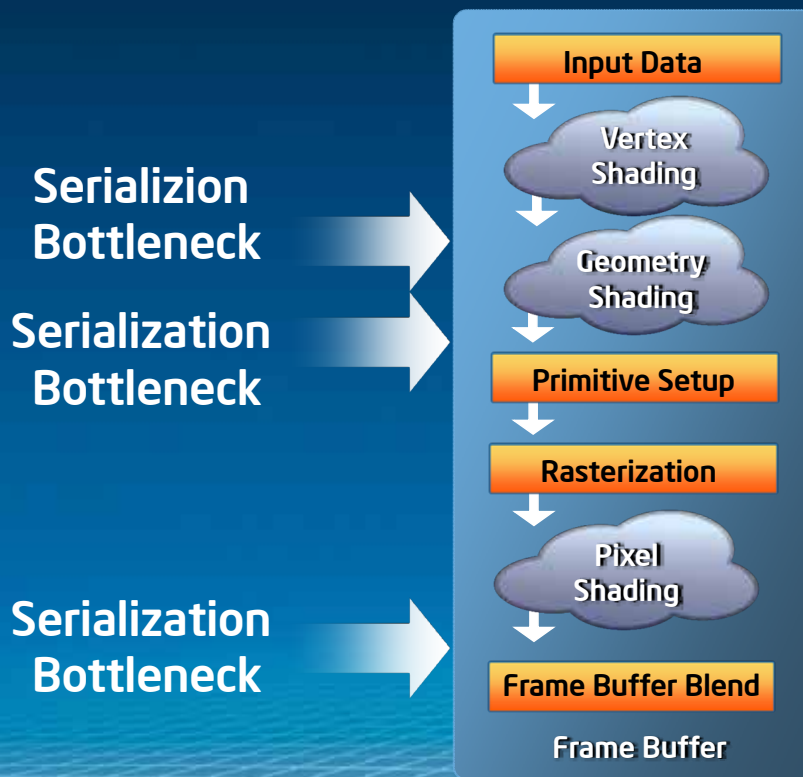


Larrabee CPU Core



Larrabee Vector Unit

# Standard HW Rendering Pipeline Is Best?

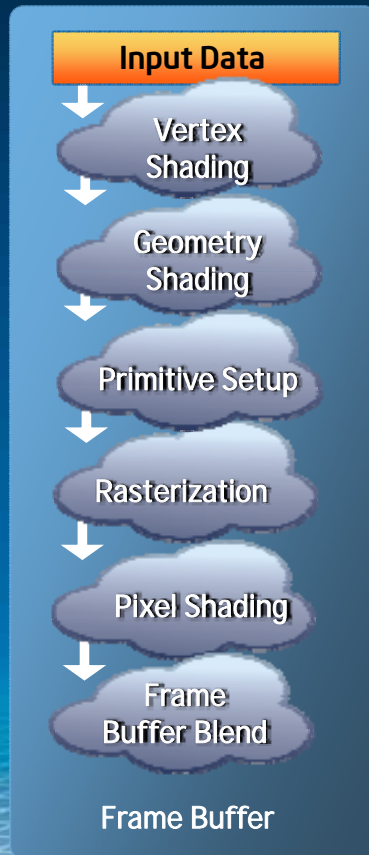


# Larrabee: Removes Serialization Bottlenecks

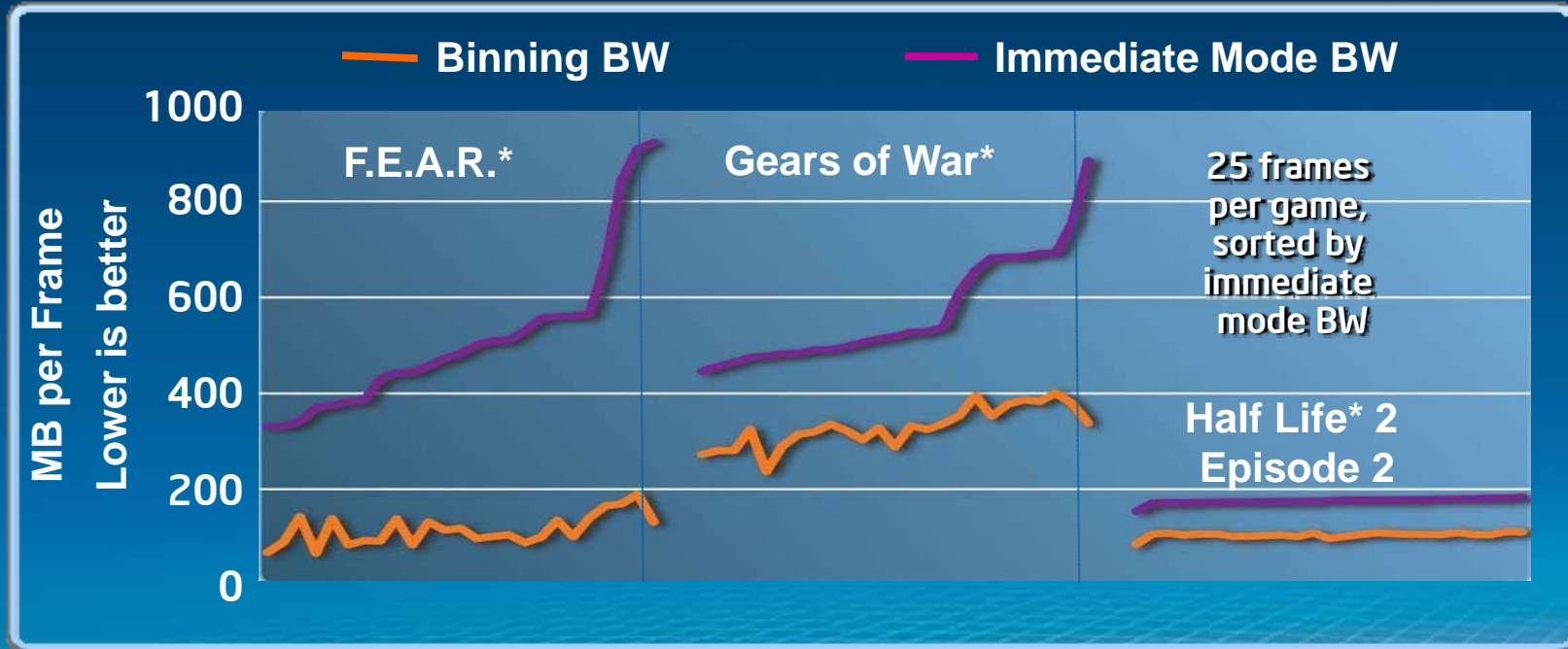
Synchronize  
By Vertex Buffers

NO Serial Processing

Synchronize  
By Tile Completion



# Larrabee Bandwidth: Binning Wins over Immediate!



Data in graph taken from Seiler, L., Carmean, D., et al. 2008. *Larrabee: A many-core x86 architecture for visual computing*. SIGGRAPH '08: ACM SIGGRAPH 2008 Papers, ACM Press, New York, NY

\* Other names & brands may be claimed as the property of others



# Graphics Processing Requires Programmability



Larrabee

Multi-core

Fully Programmable?

Multi-threading

Partially Programmable

Single Thread

Fixed Function

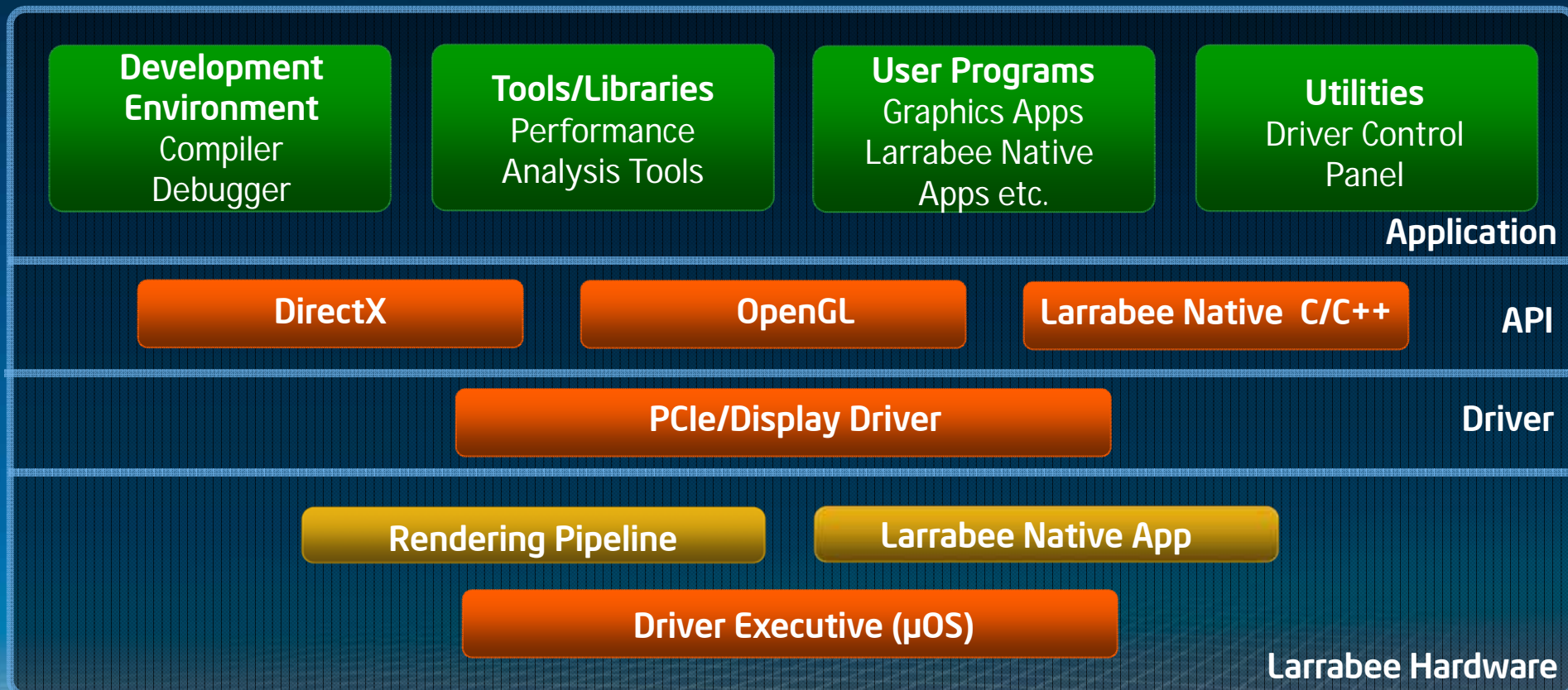
**Increasing Throughput Performance**

**Increasing Programmability**

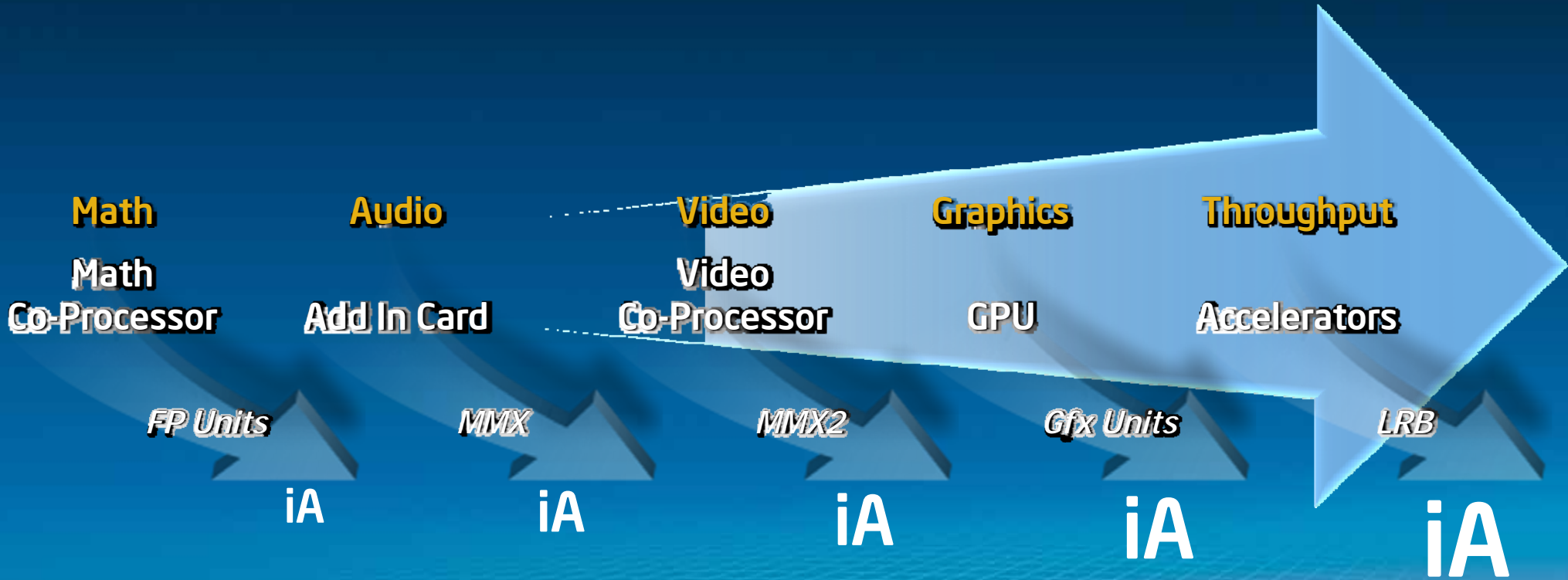
**IA: Highly Programmable**

**GPU: High Parallelism**

# Larrabee: CPU-like Software Stack



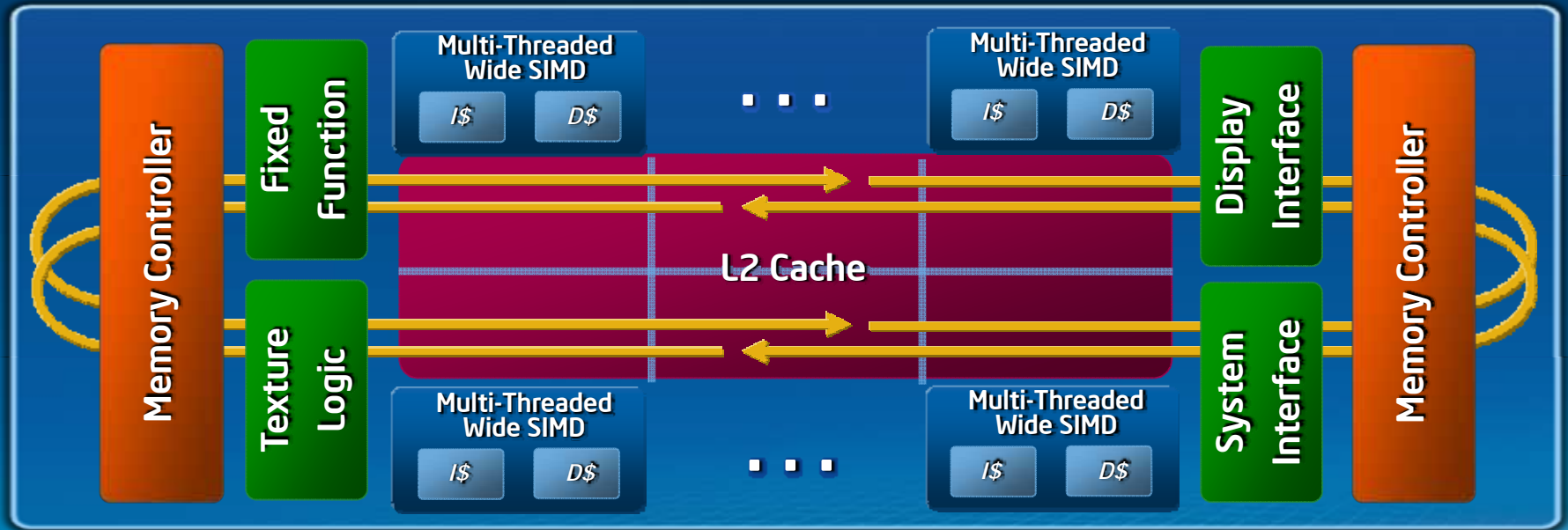
# Intel Architecture Evolution



# To Learn More About Larrabee, Please Attend

Wednesday 4:00 PM Chalk Talk "Visual Computing Trends"

Thursday 10:10 AM Larrabee: A Many-Core Intel® Architecture for Visual Computing



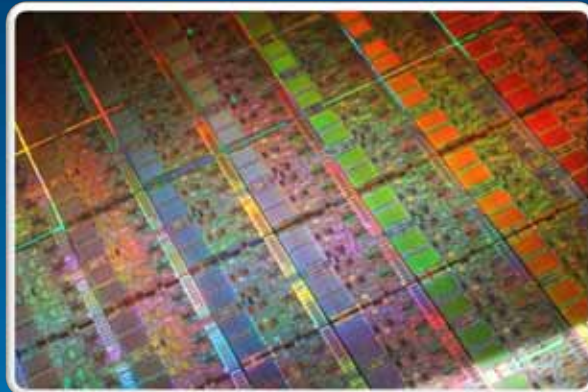
*Larrabee: The Architecture For Visual Computing*

# Intel Architecture =



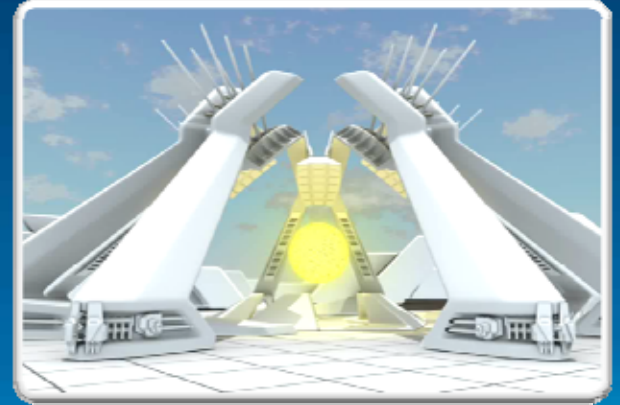
**Embedded**

+

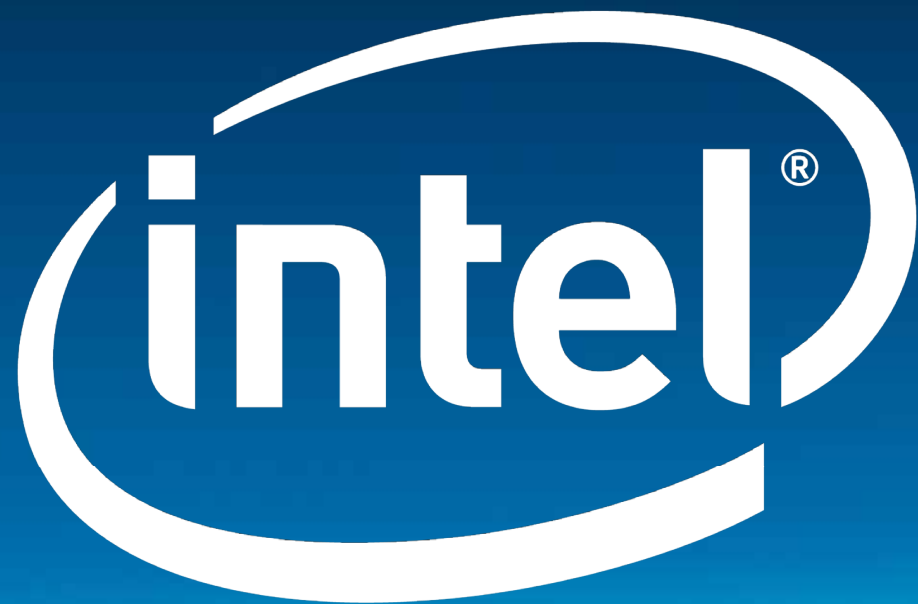


**Dynamic**

+



**Visual**



# Intel® Xeon® Processor 7400 Series Performance results Configuration details

All results published/Submitted/Approved as of August 19, 2008.

## Configuration Details:

### 4P SPECjbb\*2005 details:

Intel Xeon processor X7460, platform details: Sun\* Sun Fire\* X4450 with four Intel Xeon X7460 (6-core, 16M cache, 2.66GHz, 1066FSB), 64 GB memory, Java\* HotSpot\* 32-bit Server VM on Solaris\* v1.6.0P, Solaris\* 10 10/08. Score 531,669; submitted Aug-2008. For more information see: <http://www.spec.org/>

### 4P SPECint\*\_rate2006 details:

Intel Xeon processor X7460, platform details: Fujitsu-Siemens\* PRIMERGY\* RX600 S4 with four Intel Xeon X7460 (6-core, 16M cache, 2.66GHz, 1066FSB), 16 GB (16 \* 4GB Samsung\* DDR2 5300F, 2 rank, CL5), 64-Bit SUSE\* LINUX Enterprise S, Intel C++ Compiler for Linux32 and Linux64. Score 277, submitted Aug-2008. For more information see:

<http://www.spec.org/cpu2006/results>

### 4P TPC Benchmark\* E details:

Intel Xeon processor X7460, platform details: Dell\* PowerEdge\* R900 with four Intel Xeon processors model X7460 (6-core, 16M cache, 2.66GHz, 1066FSB), 128 GB memory, Microsoft\* SQL Server\* 2008 Enterprise x64-Edition, Microsoft\* Windows\* Server 2008 Enterprise x64-Edition. Submitted Aug-2008. For more information see: <http://www.tpc.org>. 4S/24C/24T, \$500.55/tpsE. Availability Sep-08.

### 4P vConsolidate 1.1 on VMware\* ESX Server 3.5 details: Result shown is a ratio of Xeon X7350 to Xeon X7460. Approved by VMware - August 2008

Intel Xeon processor X7460, platform details: 4U Intel® S7000FC4UR (Fox Cove) Qual Server with four Intel Xeon X7460 (6-core, 16M cache, 2.66GHz, 1066FSB), 32GB memory (16 \* 2GB FB-DIMM 667MHz Kingston\* KVR667D2D4F5/4G), Fiber Channel Adapter: 2 \* HBA Dual-Port QLE2462 PCIe\* (one idle), Storage configuration: EMC\* Clarion\* CX3-40f 4Gb 15-slot array. Single RAID controller with 4 GB cache and a battery, dual PSMs with dual AC inputs. RAID 0, SAN: 10 \* Hitachi\* 146GB 15K RAID 0 FC HDD, 2 \* DELTA DSP-1570BB, Fans: 8, VMware\* ESX Server 3.5 Update 2 RC (Build 94067).

Intel Xeon processor X7350, platform details: 4U Intel® S7000FC4UR (Fox Cove) Qual Server with four Intel Xeon X7350 (Quad-Core, 8M cache, 2.93GHz, 1066FSB), 32GB memory (16 \* 2GB FB-DIMM 667MHz Kingston\* KVR667D2D4F5/4G), Fiber Channel Adapter: 2 \* HBA Dual-Port QLE2462 PCIe\* (one idle), Storage configuration: EMC\* Clarion\* CX3-40f 4Gb 15-slot array. Single RAID controller with 4 GB cache and a battery, dual PSMs with dual AC inputs. RAID 0, SAN: 10 \* Hitachi\* 146GB 15K RAID 0 FC HDD, 2 \* DELTA DSP-1570BB, Fans: 8, VMware\* ESX Server 3.5 Update 1 GA (build 82663).

### 4P TPC Benchmark\* C details:

Intel Xeon processor X7460, platform details: Hewlett-Packard\* ProLiant\* DL580 G5 Server with four Intel Xeon X7460 (6-core, 16M cache, 2.66GHz, 1066FSB), 256GB memory, Microsoft\* SQL Server\* 2005 Enterprise x64-Edition SP2, Microsoft\* Windows\* Server 2003 R2 Enterprise x64-Edition. 4P/24C/24T, Score 634,825 @ \$1.10/tpmC. Submitted Aug-2008. Availability Sep-08.

### 8P TPC Benchmark\* C details:

Intel Xeon processor X7460, platform details: IBM\* System x\* 3950 M2 with eight Intel Xeon X7460 (6-core, 16M cache, 2.66GHz, 1066FSB), 512 GB memory, IBM DB2 9.5, Red Hat\* LINUX 5.2 (64-bit). Submitted Aug-2008. For more information see: <http://www.tpc.org>. 8S/48C/48T, \$1.99/tpmC. Availability Oct-08.

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